

PBL2002S

20 V PNP BISS loadswitch

Rev. 02 — 24 August 2009

Product data sheet

1. Product profile

1.1 General description

PNP low V_{CEsat} Breakthrough In Small Signal (BISS) transistor and NPN Resistor-Equipped Transistor (RET) in a SOT96-1 (SO8) small Surface-Mounted Device (SMD) plastic package.

1.2 Features

- Low V_{CEsat} (BISS) transistor and resistor-equipped transistor in one package
- Low threshold voltage (< 1 V) compared to MOSFET
- Low drive power required
- Space-saving solution
- Reduction of component count

1.3 Applications

- Supply line switches
- Battery charger switches
- High-side switches for LEDs, drivers and backlights
- Portable equipment

1.4 Quick reference data

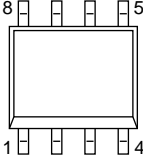
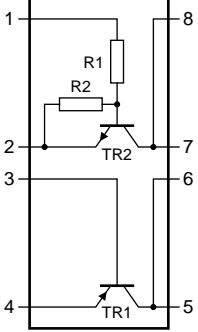
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
TR1; PNP low V_{CEsat} (BISS) transistor						
V_{CEO}	collector-emitter voltage	open base	-	-	-20	V
I_C	collector current		-	-	-3	A
R_{CEsat}	collector-emitter saturation resistance	$I_C = -2$ A; $I_B = -200$ mA	[1]	75	120	m Ω
TR2; NPN resistor-equipped transistor						
V_{CEO}	collector-emitter voltage	open base	-	-	50	V
I_O	output current		-	-	100	mA
R1	bias resistor 1 (input)		3.3	4.7	6.1	k Ω
R2/R1	bias resistor ratio		0.8	1	1.2	

[1] Pulse test: $t_p \leq 300$ μ s; $\delta \leq 0.02$

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	input (base) TR2		
2	GND (emitter) TR2		
3	base TR1		
4	emitter TR1		
5	collector TR1		
6	collector TR1		
7	output (collector) TR2		
8	output (collector) TR2		

006aaa813

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PBLS2002S	SO8	plastic small outline package; 8 leads; body width 3.9 mm	SOT96-1

4. Marking

Table 4. Marking codes

Type number	Marking code
PBLS2002S	LS2002S

5. Limiting values

Table 5. Limiting values

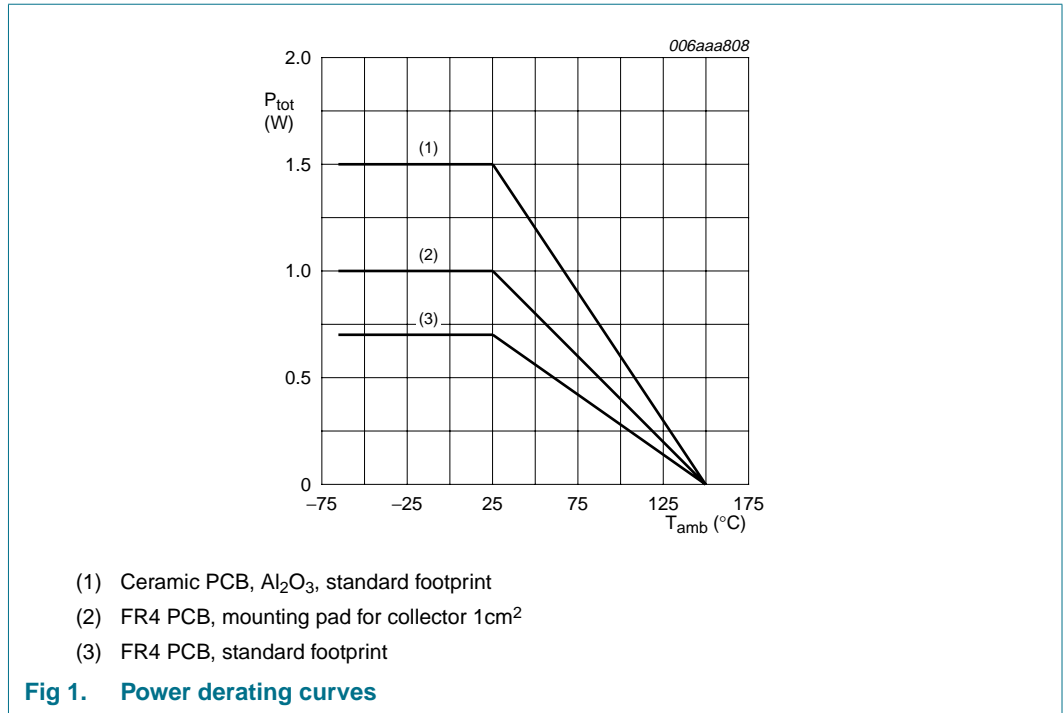
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit	
TR1; PNP low V_{CEsat} (BISS) transistor						
V_{CBO}	collector-base voltage	open emitter	-	-20	V	
V_{CEO}	collector-emitter voltage	open base	-	-20	V	
V_{EBO}	emitter-base voltage	open collector	-	-5	V	
I_C	collector current		-	-3	A	
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	-5	A	
I_B	base current		-	-0.5	A	
I_{BM}	peak base current	single pulse; $t_p \leq 1$ ms	-	-1	A	
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]	-	0.55	W
			[2]	-	0.87	W
			[3]	-	1.43	W
TR2; NPN resistor-equipped transistor						
V_{CBO}	collector-base voltage	open emitter	-	50	V	
V_{CEO}	collector-emitter voltage	open base	-	50	V	
V_{EBO}	emitter-base voltage	open collector	-	10	V	
V_I	input voltage					
		positive	-	+30	V	
		negative	-	-10	V	
I_O	output current		-	100	mA	
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	100	mA	
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]	-	0.2	W
Per device						
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]	-	0.7	W
			[2]	-	1.0	W
			[3]	-	1.5	W
T_j	junction temperature		-	150	°C	
T_{amb}	ambient temperature		-65	+150	°C	
T_{stg}	storage temperature		-65	+150	°C	

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1cm².

[3] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.



6. Thermal characteristics

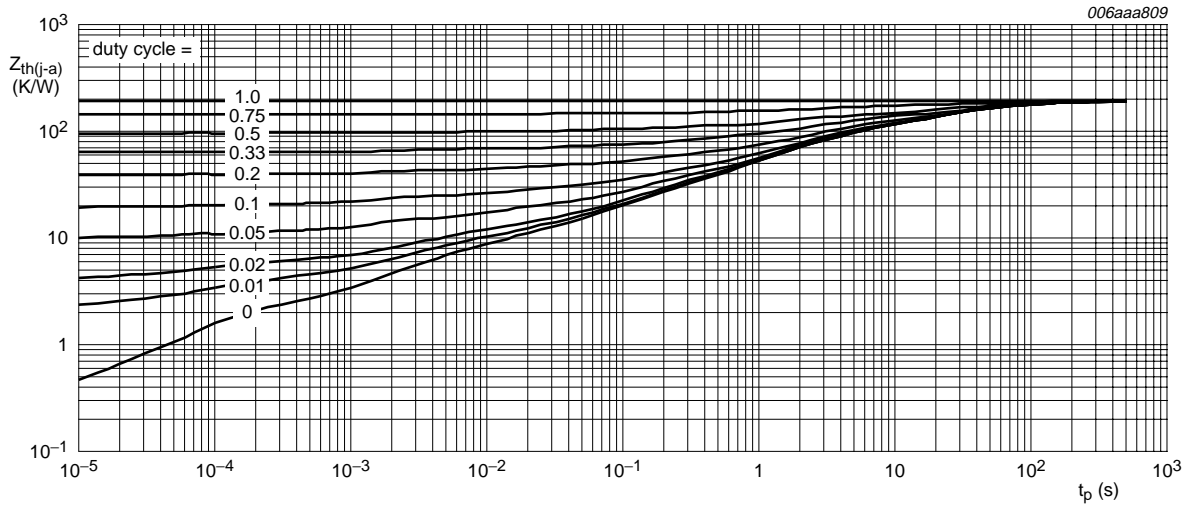
Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per device						
R _{th(j-a)}	thermal resistance from junction to ambient	in free air	[1]	-	180	K/W
			[2]	-	125	K/W
			[3]	-	85	K/W
TR1; PNP low V_{CEsat} (BISS) transistor						
R _{th(j-sp)}	thermal resistance from junction to solder point		-	-	40	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

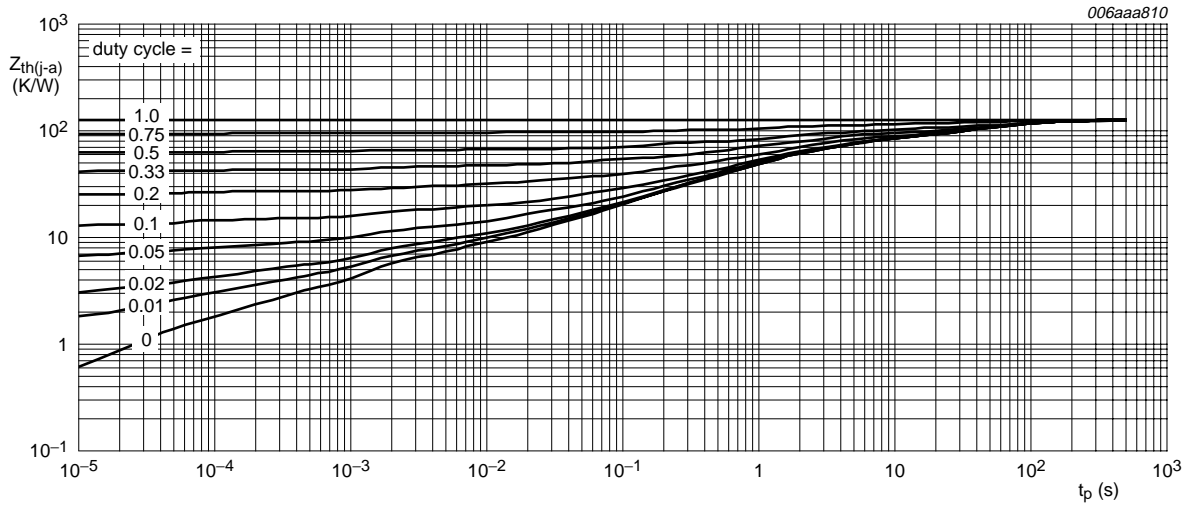
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1cm².

[3] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.



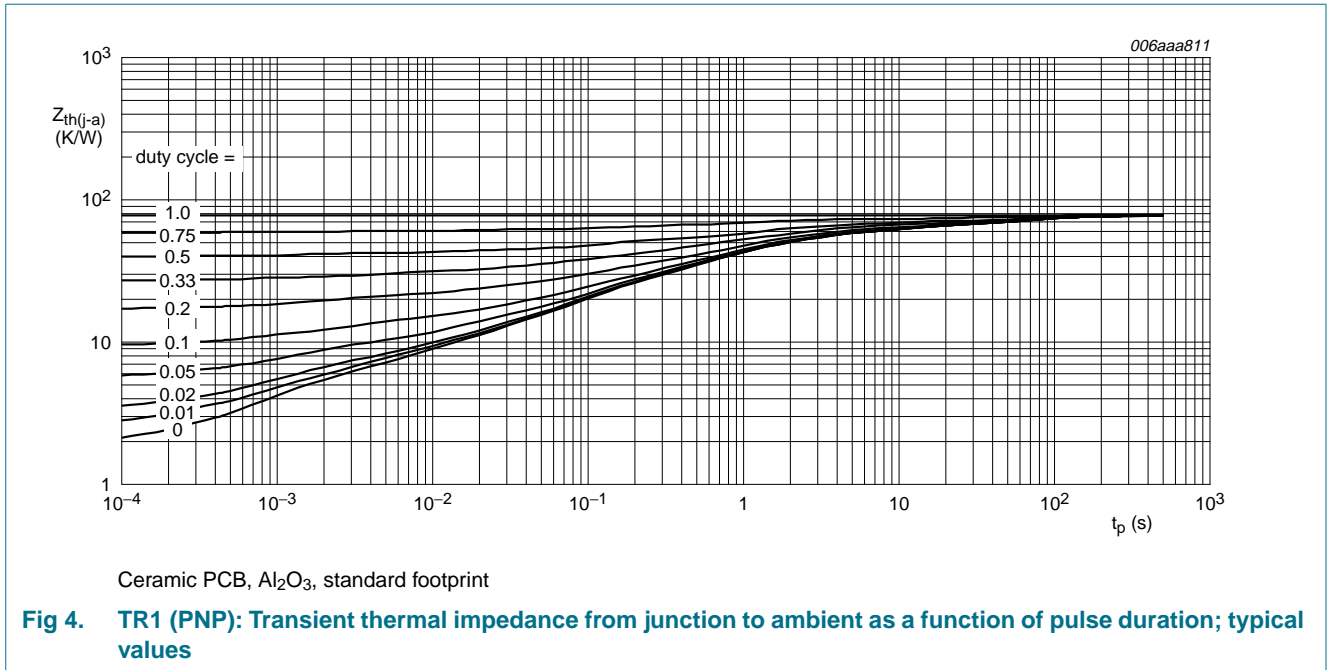
FR4 PCB, standard footprint

Fig 2. TR1 (PNP): Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for collector 1cm²

Fig 3. TR1 (PNP): Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



7. Characteristics

Table 7. Characteristics

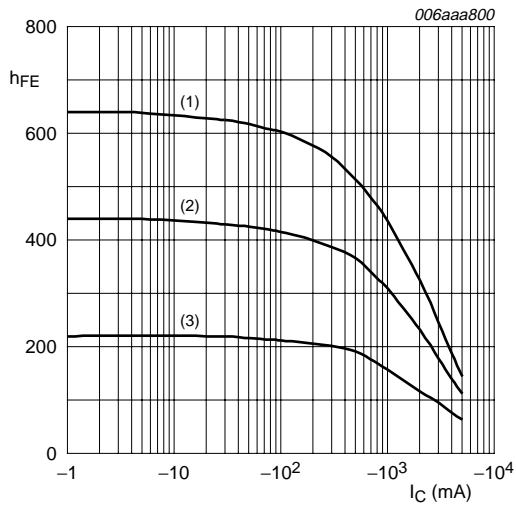
T_{amb} = 25 °C unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
TR1; PNP low V_{CEsat} (BISS) transistor						
I _{CBO}	collector-base cut-off current	V _{CB} = -20 V; I _E = 0 A	-	-	-100	nA
		V _{CB} = -20 V; I _E = 0 A; T _j = 150 °C	-	-	-50	μA
I _{CES}	collector-emitter cut-off current	V _{CE} = -20 V; V _{BE} = 0 V	-	-	-100	nA
I _{EBO}	emitter-base cut-off current	V _{EB} = -5 V; I _C = 0 A	-	-	-100	nA
h _{FE}	DC current gain	V _{CE} = -2 V; I _C = -0.1 A	220	420	-	
		V _{CE} = -2 V; I _C = -0.5 A	[1] 220	360	-	
		V _{CE} = -2 V; I _C = -1 A	[1] 200	310	-	
		V _{CE} = -2 V; I _C = -2 A	[1] 150	235	-	
		V _{CE} = -2 V; I _C = -3 A	[1] 100	180	-	
V _{CEsat}	collector-emitter saturation voltage	I _C = -0.5 A; I _B = -50 mA	[1] -	-45	-75	mV
		I _C = -1 A; I _B = -50 mA	[1] -	-90	-140	mV
		I _C = -2 A; I _B = -100 mA	[1] -	-160	-255	mV
		I _C = -2 A; I _B = -200 mA	[1] -	-150	-240	mV
		I _C = -3 A; I _B = -300 mA	[1] -	-220	-355	mV
R _{CEsat}	collector-emitter saturation resistance	I _C = -2 A; I _B = -100 mA	[1] -	80	130	mΩ
		I _C = -2 A; I _B = -200 mA	[1] -	75	120	mΩ

Table 7. Characteristics ...continued $T_{amb} = 25^{\circ}\text{C}$ unless otherwise specified

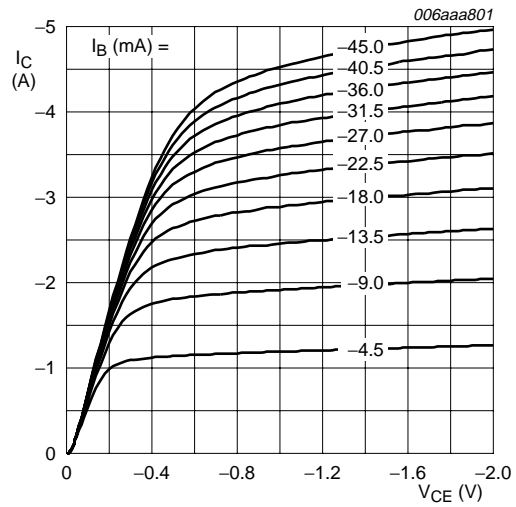
Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
V_{BEsat}	base-emitter saturation voltage	$I_C = -2\text{ A}; I_B = -100\text{ mA}$	[1]	-	-0.95	-1.1	V
		$I_C = -3\text{ A}; I_B = -300\text{ mA}$	[1]	-	-1	-1.2	V
V_{BEon}	base-emitter turn-on voltage	$V_{CE} = -2\text{ V}; I_C = -1\text{ A}$	[1]	-	-0.8	-1.2	V
t_d	delay time	$I_C = -2\text{ A}; I_{Bon} = -100\text{ mA};$ $I_{Boff} = 100\text{ mA}$	-	7	-	ns	
t_r	rise time		-	34	-	ns	
t_{on}	turn-on time		-	41	-	ns	
t_s	storage time		-	175	-	ns	
t_f	fall time		-	30	-	ns	
t_{off}	turn-off time		-	205	-	ns	
f_T	transition frequency	$I_C = -100\text{ mA}; V_{CE} = -5\text{ V};$ $f = 100\text{ MHz}$	100	-	-	MHz	
C_c	collector capacitance	$V_{CB} = -10\text{ V}; I_E = i_e = 0\text{ A};$ $f = 1\text{ MHz}$	-	-	50	pF	
TR2; NPN resistor-equipped transistor							
I_{CBO}	collector-base cut-off current	$V_{CB} = 50\text{ V}; I_E = 0\text{ A}$	-	-	100	nA	
I_{CEO}	collector-emitter cut-off current	$V_{CE} = 30\text{ V}; I_B = 0\text{ A}$	-	-	1	μA	
		$V_{CE} = 30\text{ V}; I_B = 0\text{ A};$ $T_j = 150^{\circ}\text{C}$	-	-	50	μA	
I_{EBO}	emitter-base cut-off current	$V_{EB} = 5\text{ V}; I_C = 0\text{ A}$	-	-	900	μA	
h_{FE}	DC current gain	$V_{CE} = 5\text{ V}; I_C = 10\text{ mA}$	30	-	-		
V_{CEsat}	collector-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.5\text{ mA}$	-	-	150	mV	
$V_{I(off)}$	off-state input voltage	$V_{CE} = 5\text{ V}; I_C = 100\text{ }\mu\text{A}$	-	1.1	0.5	V	
$V_{I(on)}$	on-state input voltage	$V_{CE} = 0.3\text{ V}; I_C = 20\text{ mA}$	2.5	1.9	-	V	
R1	bias resistor 1 (input)		3.3	4.7	6.1	$\text{k}\Omega$	
R2/R1	bias resistor ratio		0.8	1	1.2		
C_c	collector capacitance	$V_{CB} = 10\text{ V}; I_E = i_e = 0\text{ A};$ $f = 1\text{ MHz}$	-	-	2.5	pF	

[1] Pulse test: $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$



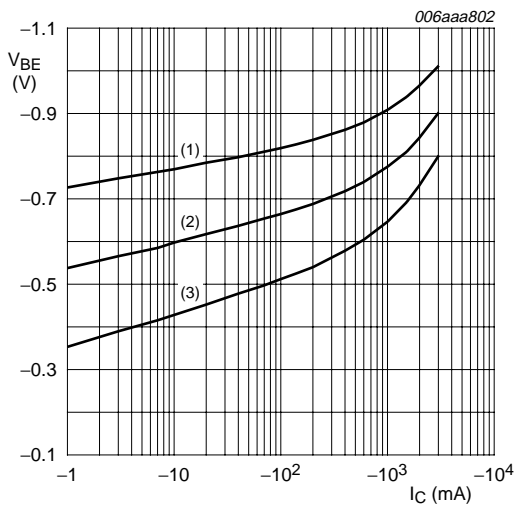
$V_{CE} = -2\text{ V}$
 (1) $T_{amb} = 100\text{ °C}$
 (2) $T_{amb} = 25\text{ °C}$
 (3) $T_{amb} = -55\text{ °C}$

Fig 5. TR1 (PNP): DC current gain as a function of collector current; typical values



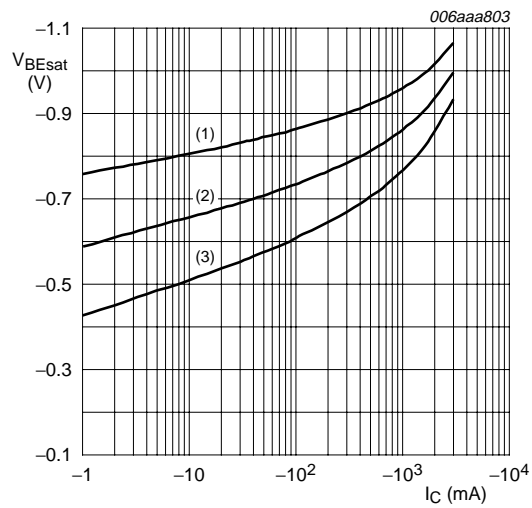
$T_{amb} = 25\text{ °C}$

Fig 6. TR1 (PNP): Collector current as a function of collector-emitter voltage; typical values



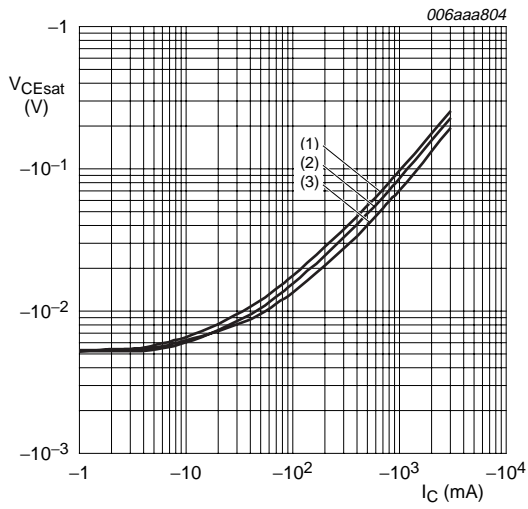
$V_{CE} = -2\text{ V}$
 (1) $T_{amb} = -55\text{ °C}$
 (2) $T_{amb} = 25\text{ °C}$
 (3) $T_{amb} = 100\text{ °C}$

Fig 7. TR1 (PNP): Base-emitter voltage as a function of collector current; typical values



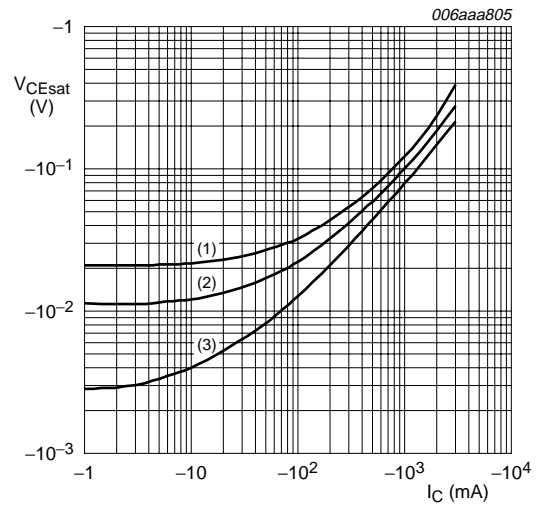
$I_C/I_B = 20$
 (1) $T_{amb} = -55\text{ °C}$
 (2) $T_{amb} = 25\text{ °C}$
 (3) $T_{amb} = 100\text{ °C}$

Fig 8. TR1 (PNP): Base-emitter saturation voltage as a function of collector current; typical values



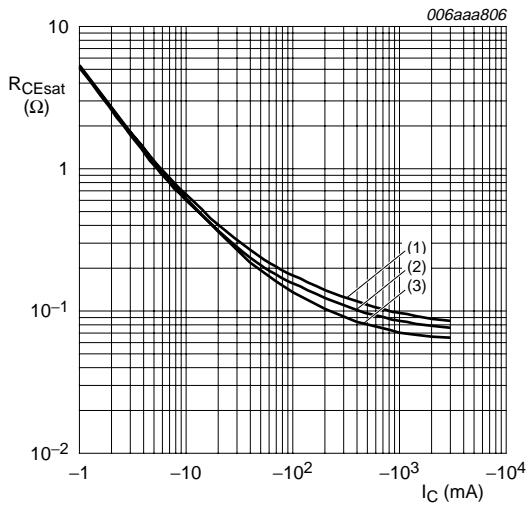
$I_C/I_B = 20$
 (1) $T_{amb} = 100\text{ }^\circ\text{C}$
 (2) $T_{amb} = 25\text{ }^\circ\text{C}$
 (3) $T_{amb} = -55\text{ }^\circ\text{C}$

Fig 9. TR1 (PNP): Collector-emitter saturation voltage as a function of collector current; typical values



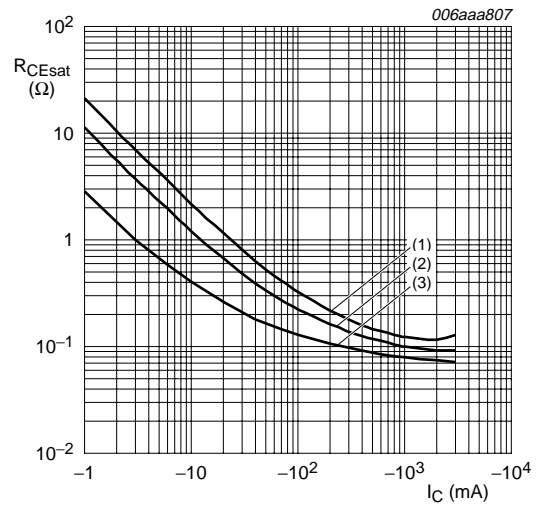
$T_{amb} = 25\text{ }^\circ\text{C}$
 (1) $I_C/I_B = 100$
 (2) $I_C/I_B = 50$
 (3) $I_C/I_B = 10$

Fig 10. TR1 (PNP): Collector-emitter saturation voltage as a function of collector current; typical values



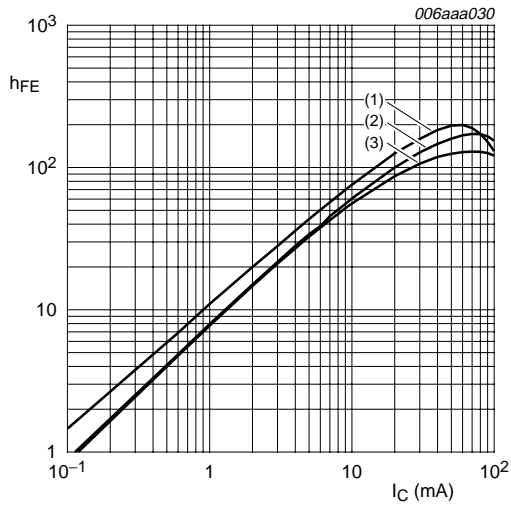
$I_C/I_B = 20$
 (1) $T_{amb} = 100\text{ }^\circ\text{C}$
 (2) $T_{amb} = 25\text{ }^\circ\text{C}$
 (3) $T_{amb} = -55\text{ }^\circ\text{C}$

Fig 11. TR1 (PNP): Collector-emitter saturation resistance as a function of collector current; typical values



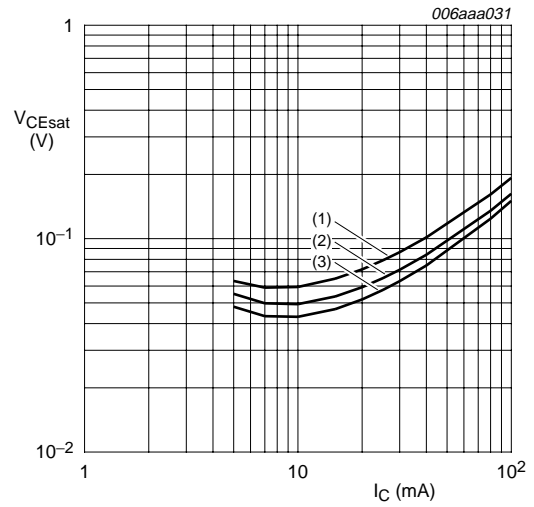
$T_{amb} = 25\text{ }^\circ\text{C}$
 (1) $I_C/I_B = 100$
 (2) $I_C/I_B = 50$
 (3) $I_C/I_B = 10$

Fig 12. TR1 (PNP): Collector-emitter saturation resistance as a function of collector current; typical values



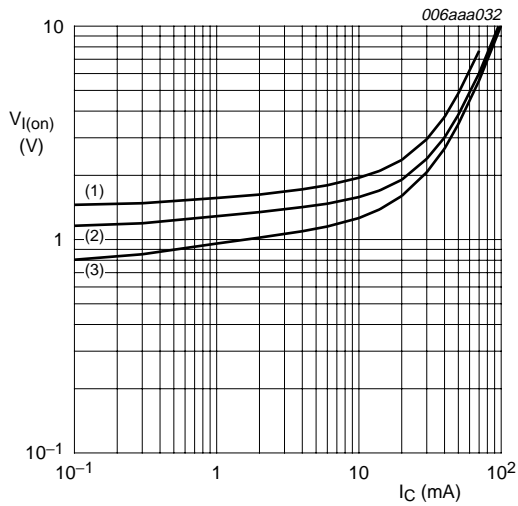
$V_{CE} = 5\text{ V}$
 (1) $T_{amb} = 150\text{ °C}$
 (2) $T_{amb} = 25\text{ °C}$
 (3) $T_{amb} = -40\text{ °C}$

Fig 13. TR2 (NPN): DC current gain as a function of collector current; typical values



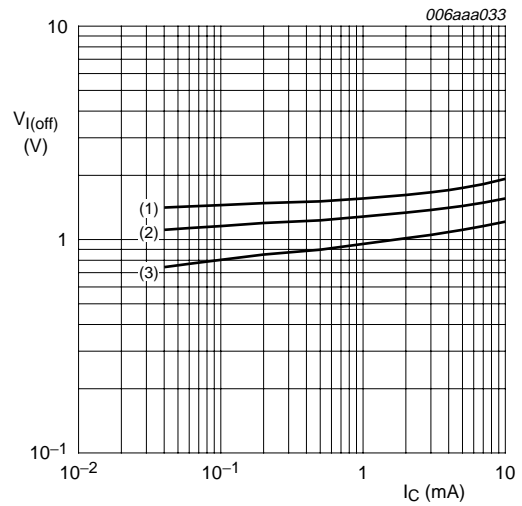
$I_C/I_B = 20$
 (1) $T_{amb} = 100\text{ °C}$
 (2) $T_{amb} = 25\text{ °C}$
 (3) $T_{amb} = -40\text{ °C}$

Fig 14. TR2 (NPN): Collector-emitter saturation voltage as a function of collector current; typical values



$V_{CE} = 0.3\text{ V}$
 (1) $T_{amb} = -40\text{ °C}$
 (2) $T_{amb} = 25\text{ °C}$
 (3) $T_{amb} = 100\text{ °C}$

Fig 15. TR2 (NPN): On-state input voltage as a function of collector current; typical values



$V_{CE} = 5\text{ V}$
 (1) $T_{amb} = -40\text{ °C}$
 (2) $T_{amb} = 25\text{ °C}$
 (3) $T_{amb} = 100\text{ °C}$

Fig 16. TR2 (NPN): Off-state input voltage as a function of collector current; typical values

8. Test information

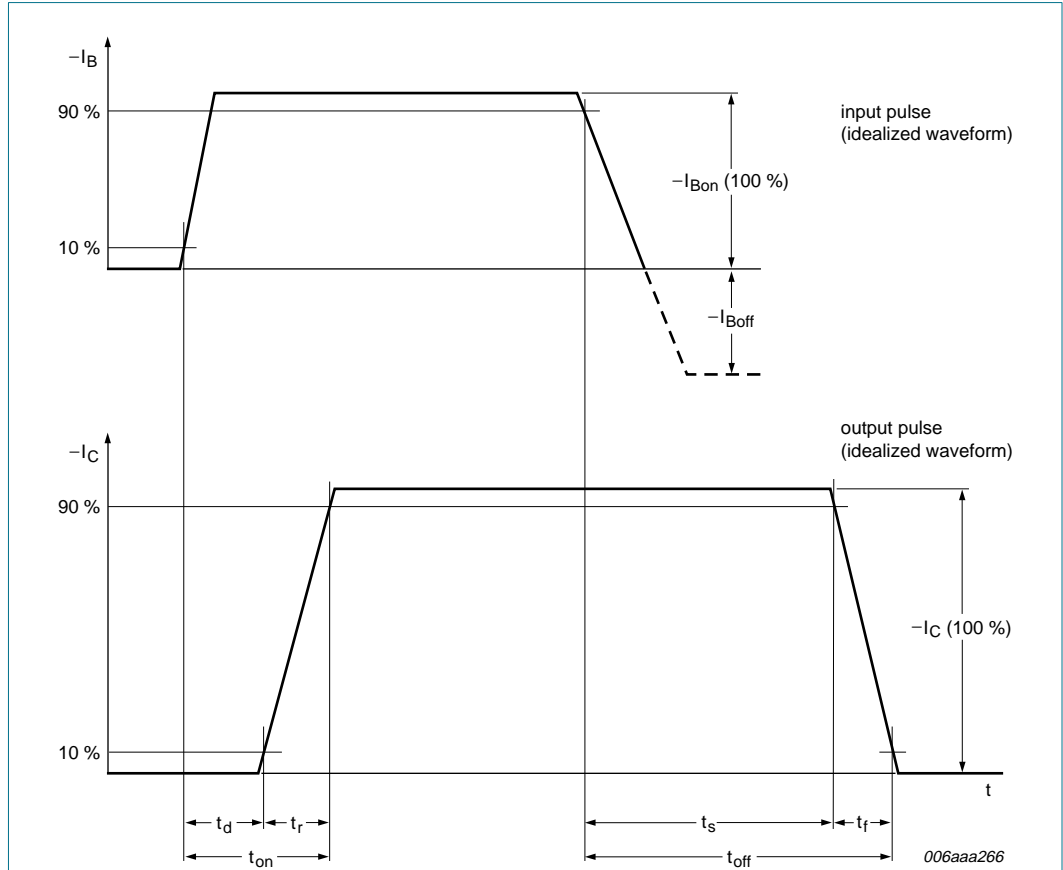
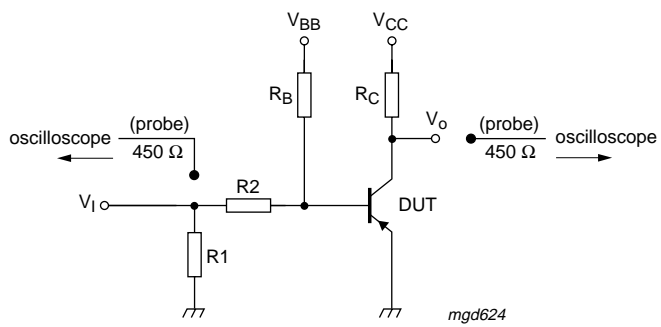


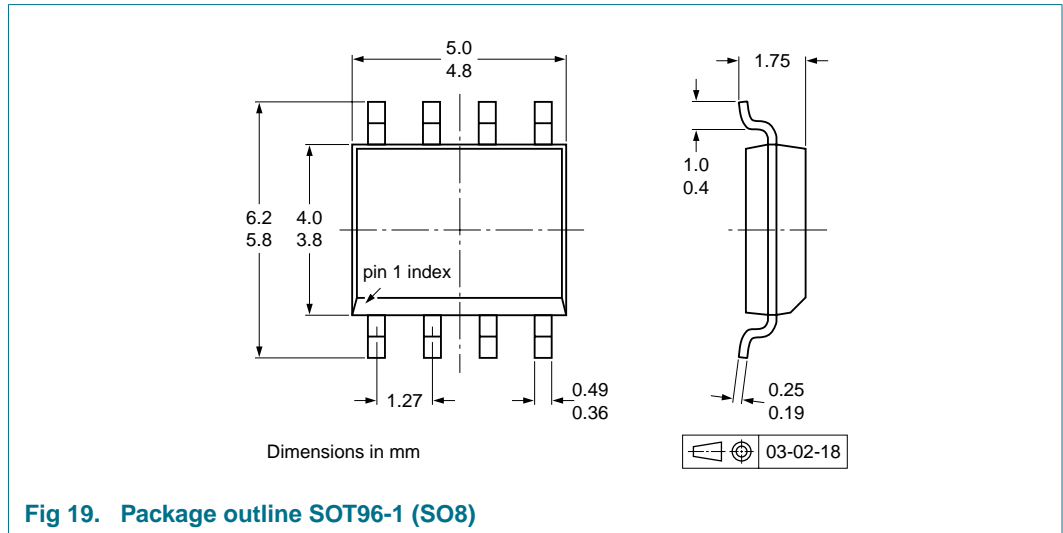
Fig 17. BISS transistor switching time definition



$I_C = -2\text{ A}$; $I_{B\text{on}} = -100\text{ mA}$; $I_{B\text{off}} = 100\text{ mA}$; $R_1 = \text{open}$; $R_2 = 25\ \Omega$; $R_B = 70\ \Omega$; $R_C = 5\ \Omega$

Fig 18. Test circuit for switching times

9. Package outline



10. Packing information

Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

Type number	Package	Description	Packing quantity	
			1000	2500
PBLS2002S	SOT96-1	8 mm pitch, 12 mm tape and reel	-115	-118

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering

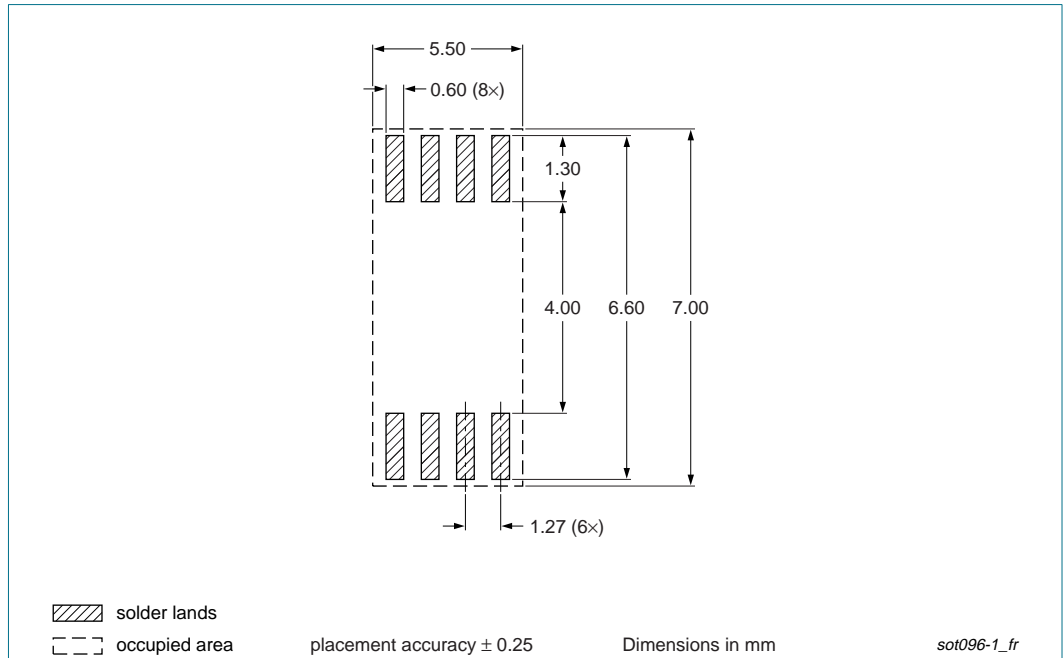


Fig 20. Reflow soldering footprint SOT96-1 (SO8)

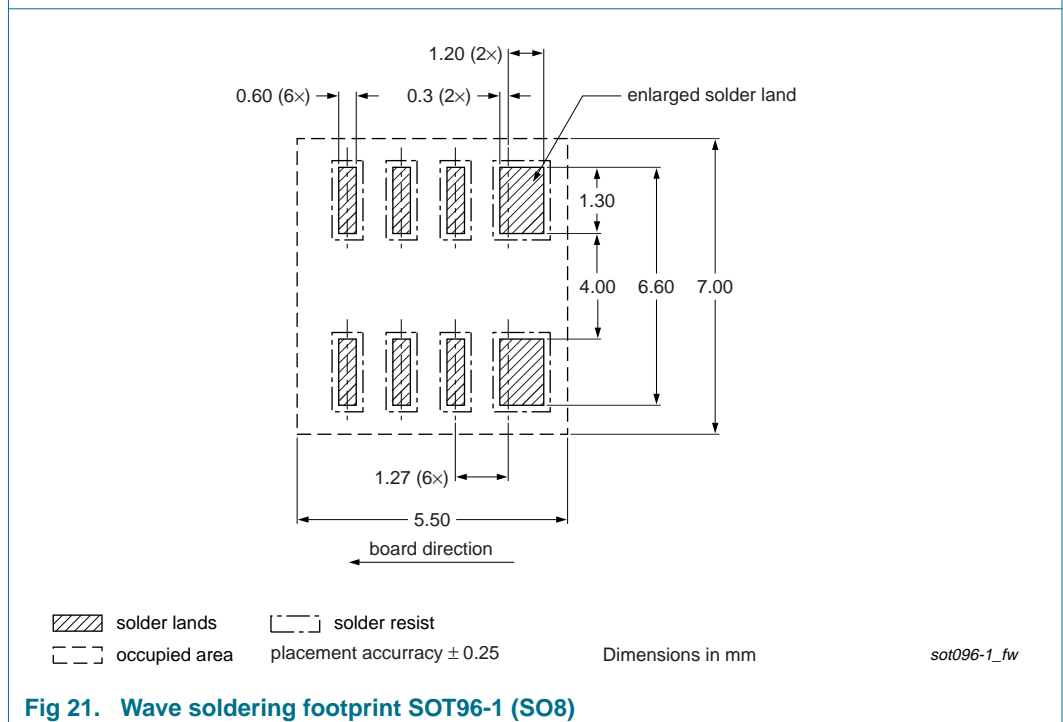


Fig 21. Wave soldering footprint SOT96-1 (SO8)

12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PBL2002S_2	20090824	Product data sheet	-	PBL2002S_1
Modifications:	<ul style="list-style-type: none">This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.			
PBL2002S_1	20060804	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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14. Contact information

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Date of release: 24 August 2009

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